Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.014”**

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**.014”**

**Top Material: Al**

 **Backside Material: AuAs**

**Bond Pad: E = .005” X .005”**

 **B = .004” X .004”**

**Backside Potential: COLLECTOR**

**APPROVED BY: DK DIE SIZE .014” X .014” DATE: 1/9/23**

**MFG: SILICON SUPPLIES THICKNESS .009” P/N: BC547B**

**DG 10.1.2**

#### Rev B, 7/1